

ABSTRACT

The present invention provides a curable composition comprising a reactive silicon group-containing polyoxyalkylene polymer which is obtained by reacting a polyoxyalkylene polymer (A) having a molecular weight distribution of 1.6 or less, a number average molecular weight of 15,000 to 50,000, and 0.8 or more reactive groups, on average, per molecule thereof with an organic compound (B) having in the molecule thereof a reactive silicon group and a functional group capable of reacting with the reactive groups of the polymer (A) in a proportion of 0.8 to 1.5 molecules of the organic compound (B), on average, per molecule of the component (A), a filler (C) and a curing catalyst (D); further in which, in the liquid components contained in the curable composition, the ratio  $y/x$  of the content  $y$  (wt%) of a component having no reactive silicon group and the content  $x$  (wt%) of a component having at least one reactive silicon group is 0.4 or less; and further in which the composition comprises a plasticizer in an amount of 10 parts by weight or less in relation to 100 parts by weight of the reactive silicon group-containing polyoxyalkylene polymer. The curable composition of the present invention improves the staining property of the cured product thereof, ensures favorable mechanical

properties favorable for a sealant such as low stress and high elongation, and is also satisfactory in workability.